

### SuperOx



# Effectiveness of laser striation for AC loss reduction in SuperOx coated conductor

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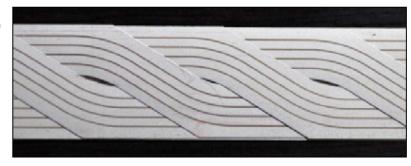
### Striations reduce magnetisation AC losses:

- Filament structures in CC is a way to reduce AC losses:
  - AC loss is proportional to the conductor squere width
- Ag
  REBCO
  Hastelloy
  Cu

  Ag
  REBCO
  Hastelloy
  Cu

  Cu

  Cu
- introducing N filaments the losses are reduced by a factor N
- Striation require sophisticated material processing:
  - Methods: Laser scribing, chemical etching,
     Mechanical scribing, inject printing.
  - Technical CC require stabilisation.
  - Up to now a lot of work done on Ag-cap conductors.



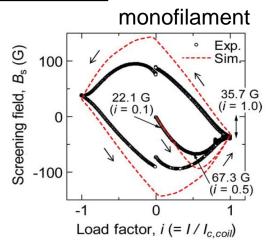
Roebel Assembled Coated Conductor
Cable with filaments

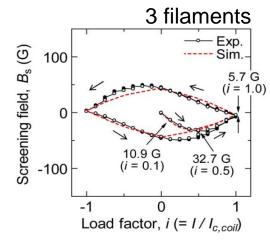


#### Striations reduce AC magnetisation losses:



#### Pancake coil:





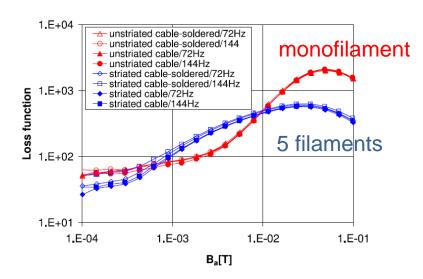
- REBCO SuperPower
- 27x2 turns
- 16.8 m tape
- B<sub>s,Coil-B</sub>/B<sub>s,Coil-A</sub> is 49%
- Y. Yanagisawa et al., IEEE Transactions on Applied Superconductivity, Vol. 25, No. 3, June 2015

#### **CORC** cabel IEE Bratislava:



- 2 cables: monofilament and 5 filaments
- REBCO Ag SuperPower 4 mm
- tape lay pitch 50 mm
- length of cable model 100 mm

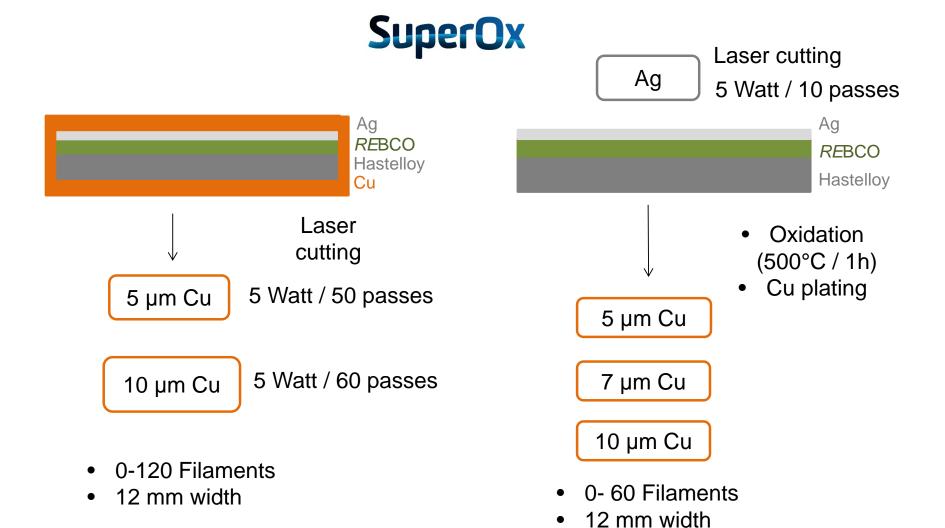
J. Souc et al., Supercond. Sci. Technol. 26 (2013) 075020 (5pp)





#### Two different structuring approaches used:

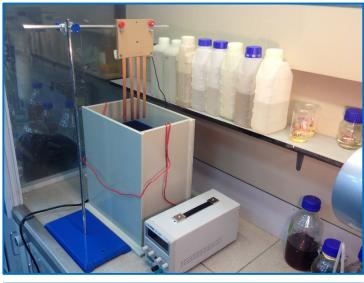


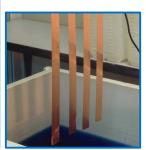




#### Electroplating process at SuperOx:







#### **Short tapes**

- Static batch process
- Plating time: 5 μm Cu: 6 min

7 μm Cu: 8,5 min

10 μm Cu: 12 min





#### Long tapes

- Continuous reel-to-reel process
- Tape speed: 5 μm Cu: 200 m/h

10 μm Cu: 100 m/h

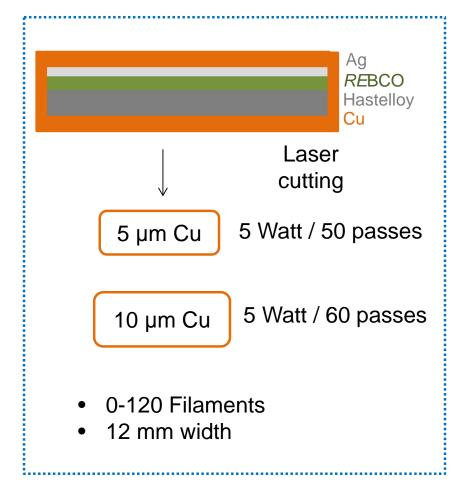
A. Molodyk "Production and integration of 2G HTS tapes into HTS devices" Tuesday M2OrC

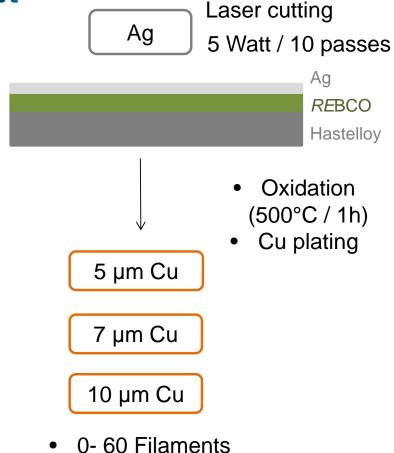


#### Laser filaments of the different tapes:



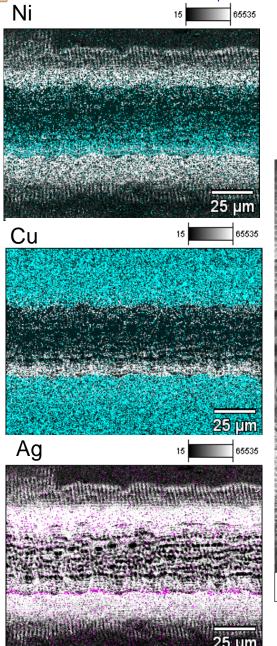
### **SuperOx**





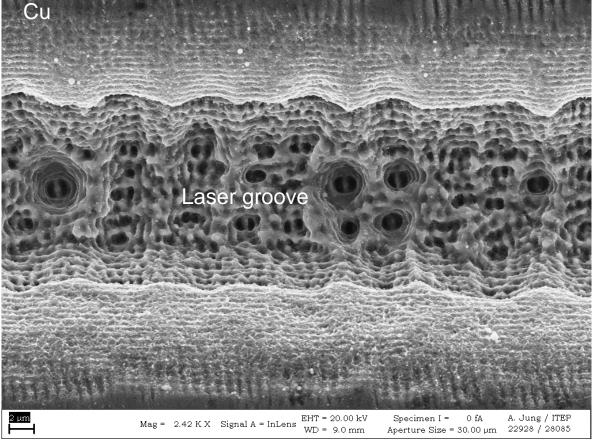
12 mm width





### Top view of the groove in tape with 5 µm Cu stabilisation:



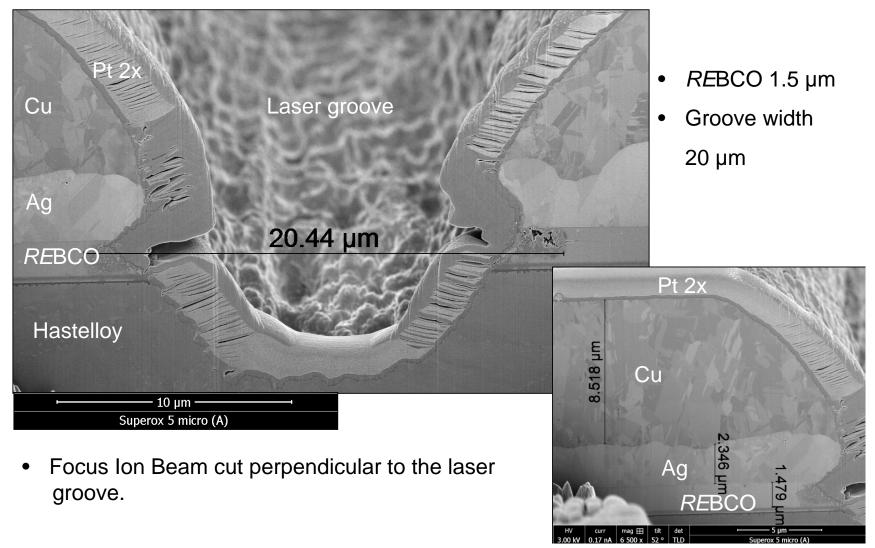


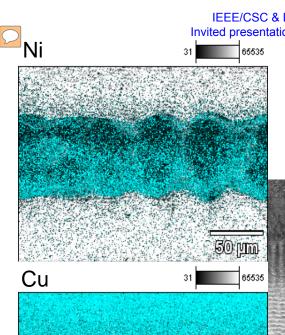
SEM and EDX of the groove top view



### Homogeneous cross-section of the tape with 5 µm Cu layer:

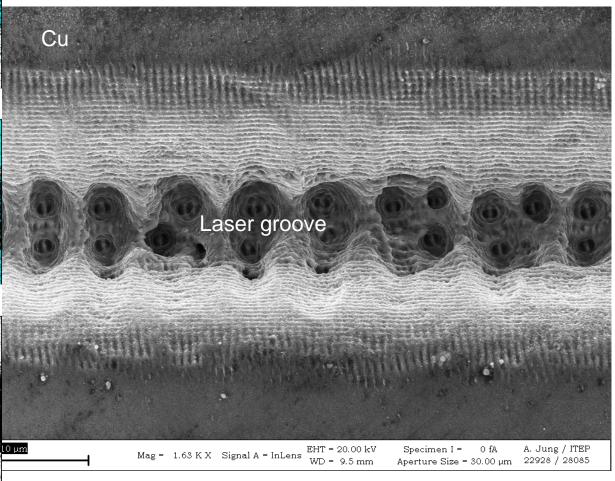






## Top view of the groove in tape with 10 µm Cu stabilisation:

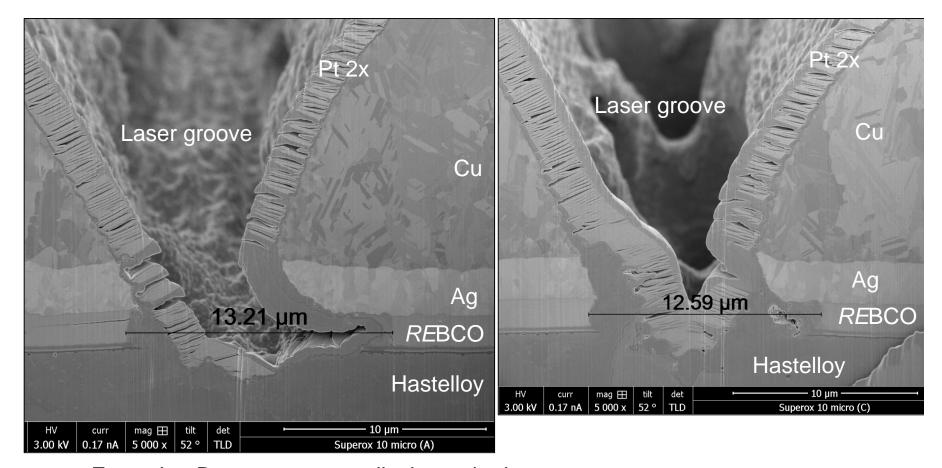






## Relatively homogeneous cross-section of the tape with 10 µm Cu layer:



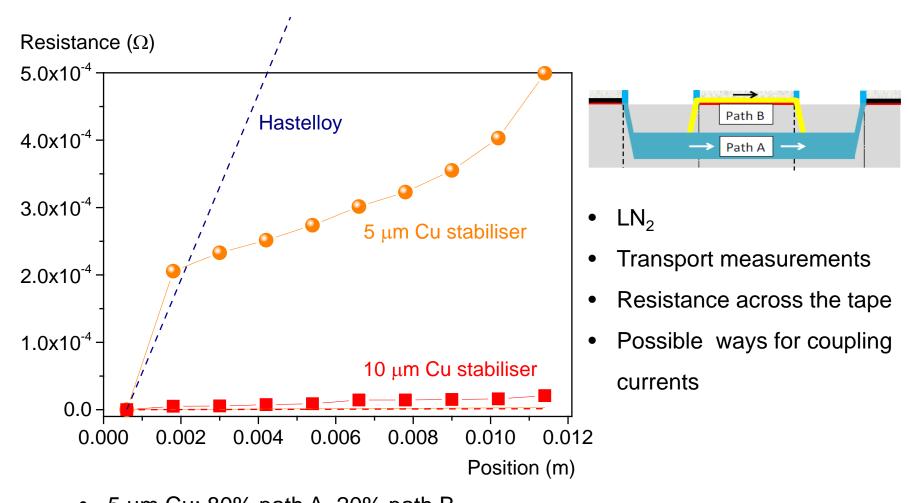


- Focus Ion Beam cut perpendicular to the laser groove
- REBCO 1.5 μm, groove width 20 μm



### Two possible current paths across the tape:



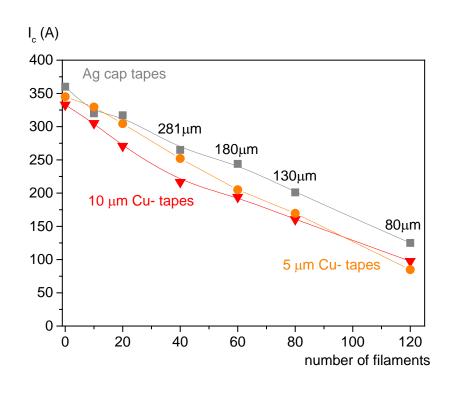


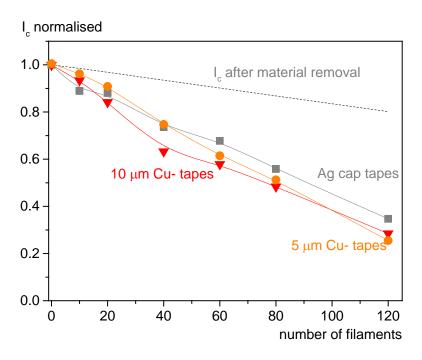
- 5 μm Cu: 80% path A, 20% path B
- 10 μm Cu: 2% path A, 98% path B



### I<sub>c</sub> redaction caused not only by material removal:







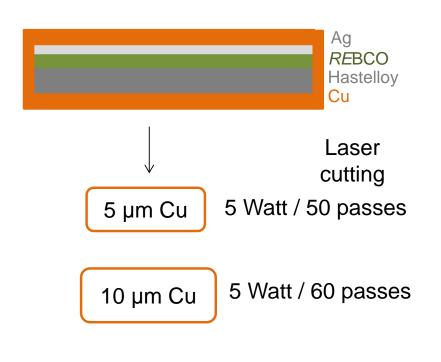
- Strong (80%) I<sub>c</sub> degradation with 120 filaments.
- Similar current reduction at tapes with 5 and 10 µm copper stabilisation.
- Stronger current redaction in Ag-cap samples than only coming from removed material.



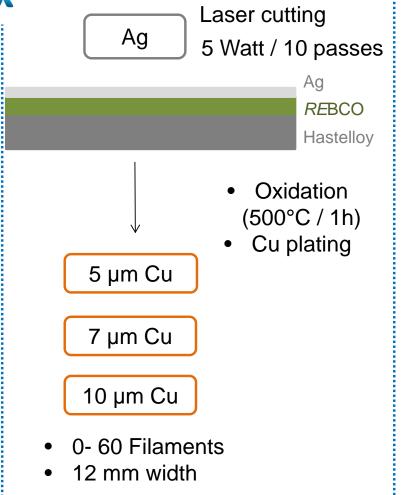
### Laser filaments of the different tapes:



### **SuperOx**



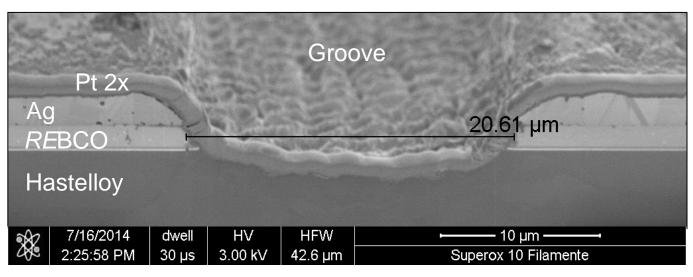
- 0-120 Filaments
- 12 mm width



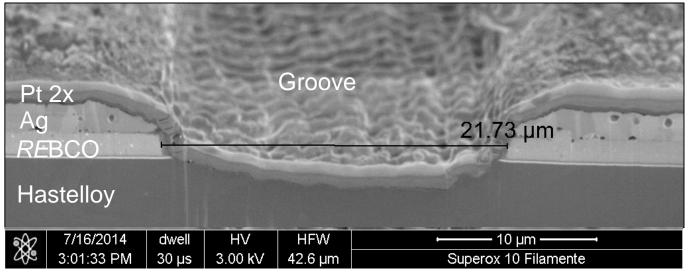


### Homogeneous cross-section of the tape with Ag cap:





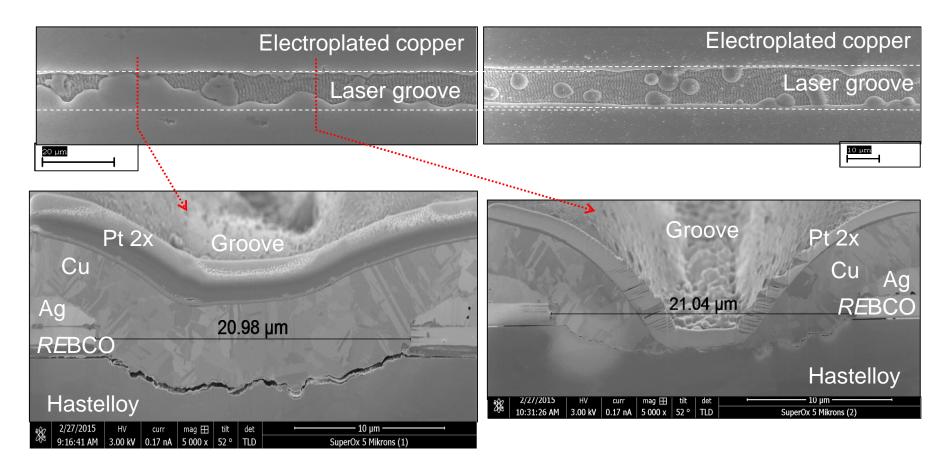
- Ag cap
- REBCO 1.5 µm
- Groove width21µm





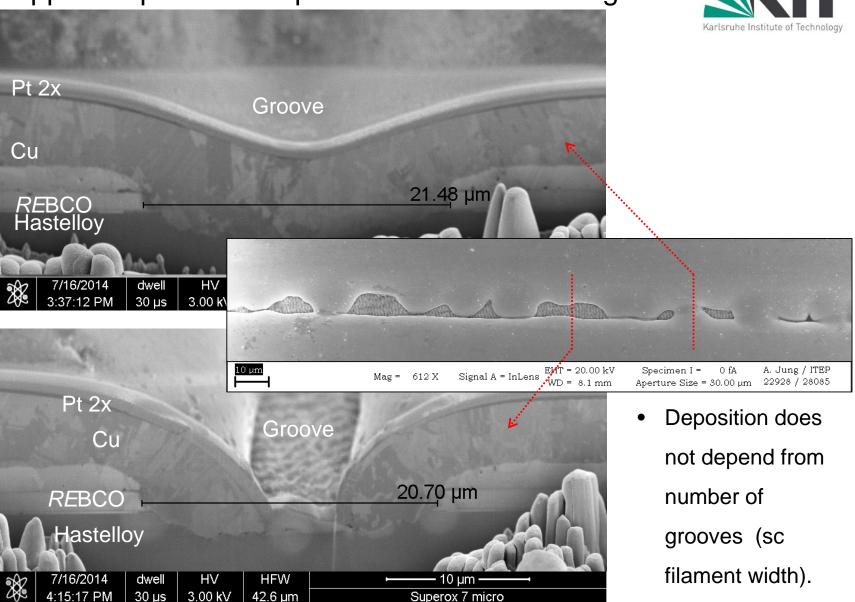
## Copper - $5 \mu m$ - partially deposited on the oxidised groove:





- Inhomogeneous deposition copper into a grooves
- Copper bridges across laser groove

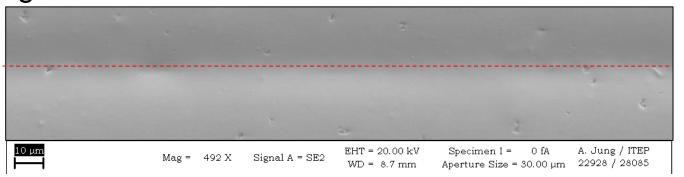
Copper - 7 µm - half deposited on the oxidised groove:



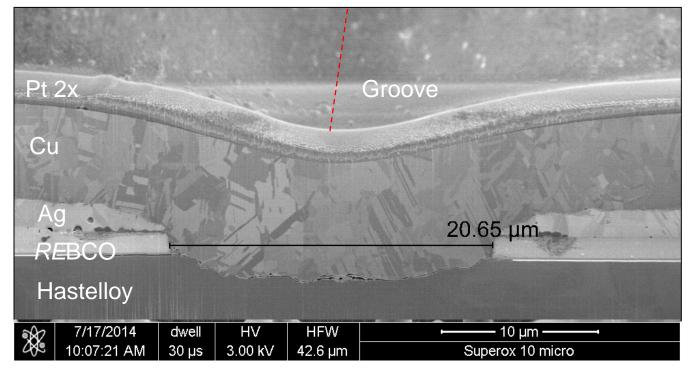


# Copper - 10 µm - deposited along entire oxidised groove:





Groove top view.

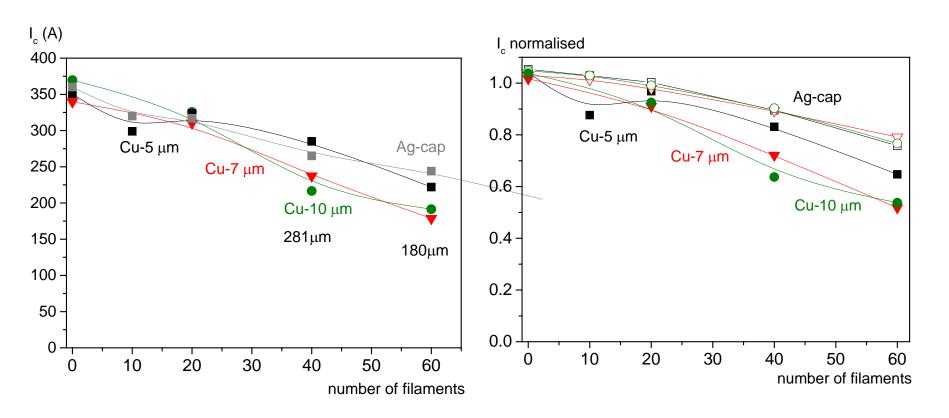


 Deposition do not depend from groove number.
 (sc filament width)



### Critical current reduction due to used electrolyte:



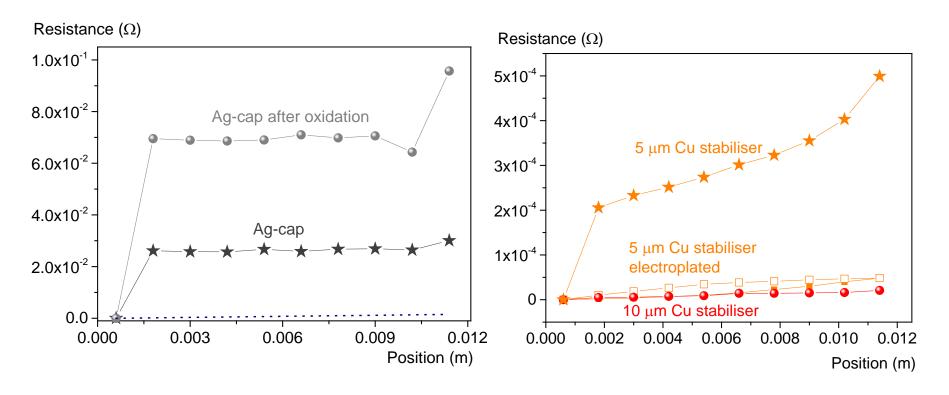


- Ag-cap tape non-oxidised
- Negligible reduction in I<sub>c</sub> with 5 µm Cu
- Small I<sub>c</sub> reduction due to electrolyte
- Smaller reduction with 5 µm Cu
- Stronger reduction with 7 and 10 μm Cu

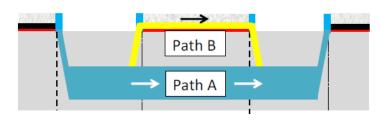


# Current flow across Cu bridges in electroplated samples:





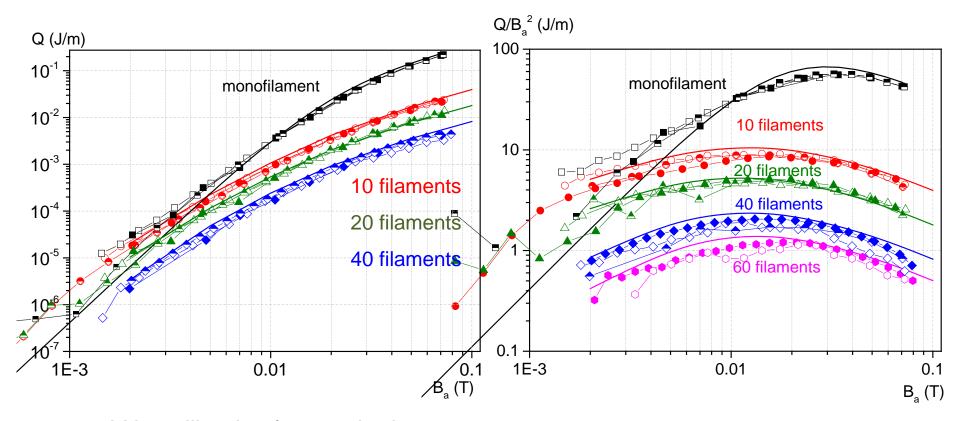
- Oxidation enhance resistance (Ag cap)
- Electroplated samples: current path B
- Ag-cap samples: current path A





### No coupling losses at oxidised Ag cap tapes:



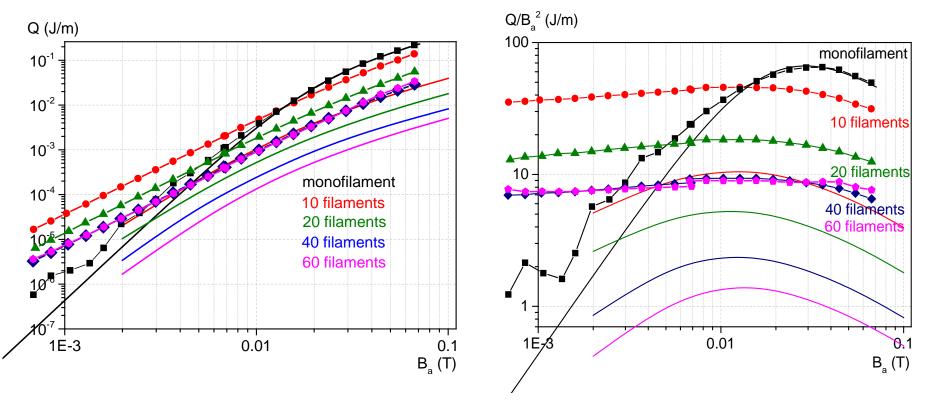


- LN<sub>2</sub>, calibration free method
- Fully uncoupled limit analytical formula from Mawatari PRB 1996 (lines)
- Different frequencies measured: 12, 72, 130 Hz



# Coupling losses visible at Ag cap after 5 µm Cu electroplating:



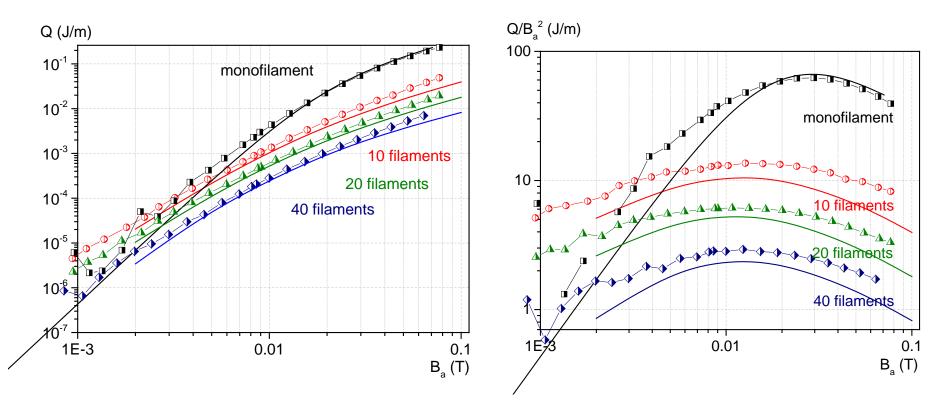


- LN<sub>2</sub>, calibration free method, frequency 72 Hz
- Fully uncoupled limit analytical formula from Mawatari PRB 1996 (lines)
- Coupling losses higher than magnetisation losses



### Magnetisation loss reduction at low frequencies:





- LN<sub>2</sub>, calibration free method, Frequency 6 Hz
- Fully uncoupled limit analytical formula from Mawatari PRB 1996 (lines)
- Coupling losses negligible, reduction of the magnetisation loss



#### Summary:



Two different methods were applied:

top down: laser cutting through Cu+Ag+REBCO.

bottom up: laser cutting through Ag+REBCO and electroplating.

- Both methods depend strongly on material homogeneity.
- Laser cut narrow, well defined lines in the case of thin materials.
- Industrial copper plating process at SuperOx was used.
- Coupling loss due to resistive bridges on the laser groove observed.
- Low AC losses at low frequencies were obtained (close to theory expectations).
- Loss reduction by factor of 30 at 100 mT applied magnetic field with 40 filaments, when I<sub>c</sub> reduced by 20% (6 Hz).